



Material Content Data Sheet



Sales Product Name	IFX1763LD V33			Issued	3. April 2018			
MA#	MA001093918							
Package	PG-TSON-10-2			Weight*	31.79 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.268	3.99	3.99	39886	39886
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		104	
	non noble metal	zinc	7440-66-6	0.013	0.04		417	
	non noble metal	iron	7439-89-6	0.265	0.83		8345	
wire	non noble metal	copper	7440-50-8	10.773	33.88	34.76	338850	347716
	non noble metal	copper	7440-50-8	0.039	0.12	0.12	1241	1241
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.12		1164
	plastics	epoxy resin	-	1.906	6.00		59959	
	inorganic material	silicondioxide	60676-86-0	16.564	52.12	58.24	521005	582128
leadfinish	non noble metal	tin	7440-31-5	0.370	1.16	1.16	11641	11641
plating	noble metal	silver	7440-22-4	0.064	0.20	0.20	2021	2021
glue	plastics	epoxy resin	-	0.122	0.38		3842	
	noble metal	silver	7440-22-4	0.366	1.15	1.53	11525	15367
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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